## JACOBSON HOLMAN, PLLC

400 SEVENTH STREET, N.W. WASHINGTON, D.C. 20004-2201

## LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

ATTY. D	OCKET	NO.: P690841			ART UNIT:	Not Yet Assigned	
SERIAL NO.: <u>Not Yet Assigned</u>				FILING	FILING DATE: August 22, 2003		
APPLICA	NT(S)	: Jung W	ook LIM, et	al. TODAY'S	DATE:A	ugust 22, 2003	
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			U.S. PA	TENT DOCUMENTS			
*EXAMINER		DOCUMENT			INT'L	SUB- FILING DATE	
INITIAL		NUMBER	DATE	NAME	CLASS	CLASS (If Appropriate)	
A O							
VIC	AA	6,416,822	7/09/02	Chiang, et al.	B05D	3/00 3/19/01	
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M	AB	6,468,924	10/22/02	Lee, et al.	H01L	21/31 5/31/01	
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			FOREIGN	PATENT DOCUMENTS			
		DOCUMENT				SUB- TRANSLATION	
		NUMBER	DATE	COUNTRY	CLASS	CLASS (YES) (NO)	
No							
TTC	AC	2002-46431	06/21/02	KOREA (ROK)	H01L	29/108 X	
	AD						
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Δ	OTHER	ART (Includ	ing Author,	Title, Date, Per	rtinent Pa	ages, Etc.)	
A							
MC	AF	Jin-Seong H	ark, et al	.; "Plasma-Enhand	ced Atomio	c Layer Deposition	
		of Ta-N Thi	n Films";	Journal of The El	lectrocher	mical Society, 149	
<b>/</b> A		(1) C28-C32	(2002).				
12							
VC	AG	Hyun-Jung S	ong, et al	.; "Increment of	the Diel	ectric Constant of	
•						de Growth on S:	
		Substrates"	: Electtroc	hemica and Solid-	State Let	ters, 4(7) F13-F1	
		(2001).					
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